



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-09-13
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STU5N62K3	TXIK*TZ62B62	A	3068	2017-09-13
Amount	UoM	Unit type	ST ECOPACK Grade	
310.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NA	NA	NA		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DIP	6.1-6.5-2.3	3	Through-hole	
Comment	IPAK TO-251			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.23	Die back side metal - Leadframe metal	755
Lead	5.46	Soft solder	17613

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	TXIK*1262B62					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	6.125	mg	supplier	die	Silicon (Si)	7440-21-3		5.910	mg	964898	19065
				supplier	metallization	Aluminium (Al)	7429-90-5		0.078	mg	12734	252
				supplier	Passivation	Silicon Nitride	12033-89-5		0.025	mg	4082	81
				supplier	Passivation	Silicon Oxide	7631-86-9		0.060	mg	9796	194
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.003	mg	490	10
				supplier	back side metallization	Gold (Au)	7440-57-5		0.009	mg	1469	29
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.040	mg	6531	129
				supplier	alloy	Copper (Cu)	7440-50-8		181.495	mg	997544	585468
				supplier	alloy	Iron (Fe)	7439-89-6		0.182	mg	1000	587
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.055	mg	302	177
Leadframe	Copper & its alloys	181.942	mg	supplier	metallization	Nickel (Ni)	7440-02-0		0.194	mg	1066	626
				supplier	metallization	Phosphorus (P)	12185-10-3		0.016	mg	88	52
				supplier	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	5.460	mg	955046	17611
				supplier	solder	Silver (Ag)	7440-22-4		0.143	mg	25013	461
				supplier	solder	Tin (Sn)	7440-31-5		0.114	mg	19941	368
Soft solder	Solder	5.717	mg	JIG - R	solder	Aluminium (Al)	7429-90-5		0.323	mg	996914	1042
				supplier	wire	Magnesium (Mg)	7439-95-4		0.001	mg	3086	3
Bonding wires	Other inorganic materials	0.324	mg	supplier	wire	Silica, vitreous	60676-86-0		98.165	mg	874997	316661
				supplier	compound	Tetramethyl-biphenyl-diyl-bis oxymethylene-b	EC 413-900-7		4.488	mg	40004	14477
				supplier	compound	Epoxy Resin	25068-38-6		3.366	mg	30003	10858
				supplier	compound	phenol resin	29690-82-2		5.609	mg	49996	18094
				supplier	compound	Carbon black	1333-86-4		0.561	mg	5000	1810
Connections coating	Solder	3.703	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		3.703	mg	1000000	11945